MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet



SOD-523

MARKING:S1



BAS716 FAST SWITCHING DIODE

FEATURES

- Small Package
- Low Reverse Current
- Fast Switching Speed
- Surfce Mount Package Ideally Suited for Automatic Insetion

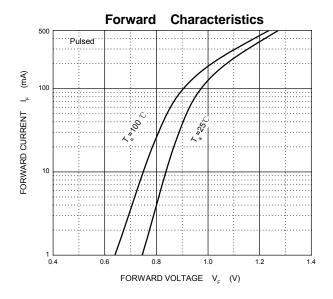
MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

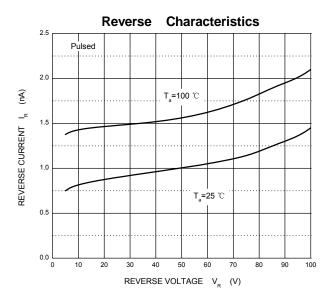
Symbol	Paramete	Value	Unit	
V_{RM}	Non-Repetitive Peak Reverse Voltage	100	100 V	
V_{RRM}	Peak Repetitive Reverse Voltage	75 V		
V _{RWM}	Working Peak Reverse Voltage			
V _{R(RMS)}	RMS Reverse Voltage	53	V	
lo	Average Rectified Output Current	200	mA	
I _{FSM}	Non-Rpetitive Peak Forward Surge Current @t=8.3ms	1	А	
P _D	Power Dissipation	225	mW	
R _{OJA}	Thermal Resistance from Junction to Ambient	556	°C/W	
Tj	Junction Temperature	150	°C	
T _{stg}	Storage Temperature	-55~+150	°	

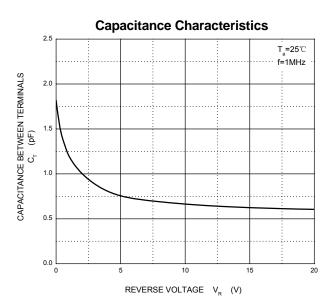
ELECTRICAL CHARACTERISTICS(T_a=25℃ unless otherwise specified)

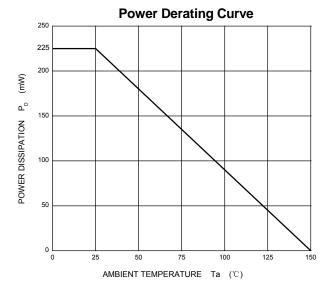
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	$V_{(BR)}$	I _R =100μA	75			V
Reverse current	I _R	V _R =75V			5	nA
		V _R =100V			80	nA
		I _F =1mA			0.9	V
Famuumd valtama	V _F	I _F =10mA			1	V
Forward voltage		I _F =50mA			1.1	V
		I _F =150mA			1.25	V
Total capacitance	C _{tot}	V _R =0V,f=1MHz		2		pF
Reverse recovery time	t _{rr}	I _F = I _R =10mA, I _{rr} =0.1*I _R			3	μs

Typical Characteristics



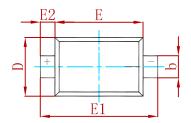


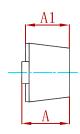


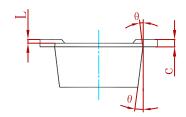




PACKAGE MECHANICAL DATA

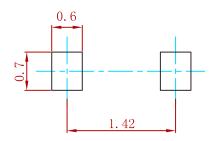






	Dimoneione	In Millimotore	Dimensions In Inches		
Symbol	Dimensions In Millimeters				
	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
E	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
θ	7° REF		7° F	REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.05mm.
 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS716	SOD-523	3000



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